EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	0	siemitsu.as.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/06 15:40
S2	13307	seimitsu.as.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/02 09:28
S3	7	laser and tape and dicing and S2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/16 11:59
S4	1191	laser and tape and dicing and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/14 08:27
S5	304	street and S4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/14 08:59
S6	54	yag and S5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/14 08:59
S7	15	("5552345").URPN.	USPAT	OR	ON	2005/03/14 09:05
S8	9	("4543464" | "4716270" | "4861964" | "4865686" | "5151389" | "5185295" | "5552345" | "5922224" | "6257224").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/03/14 09:08
S9	2	("6737606").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/16 10:12

S10	11	("4355457" | "4610079" | "5091331" | "5302554" | "5356081" | "5543365" | "5552345" | "5902499" | "5904546" | "6427676" | "6555294").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/16 10:13
S11	13	("5543365").URPN.	USPAT	OR	ON	2005/08/16 10:14
S12	9	("20010040152" | "20020115235" | "4610079" | "5543365" | "6211488" | "6252197" | "6271102" | "6407360" | "6512196").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/16 10:19
S13	22	("4015175" | "4104697" | "4292576" | "4312115" | "4721977" | "4729971" | "4814296" | "4846032" | "4900283" | "4985982" | "5000811" | "5217907" | "5219796" | "5272114" | "5369060" | "5477065" | "5786266" | "5843831" | "5858808" | "5943591" | "5998238" | "6124148").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/16 10:22
S14	2	("6734083").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/16 11:57
S15	0	("6734083").URPN.	USPAT	OR	ON	2005/08/16 11:57
S16	9	("20010040152" | "20020115235" | "4610079" | "5543365" | "6211488" | "6252197" | "6271102" | "6407360" | "6512196").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/16 11:57
S17	7524	laser and (cutting adj wheel or dicing) and substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/16 12:00
S18	3528	(tape or adhesive) and S17	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/16 12:00

S19	690	melt and S18	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/16 12:01
S20	155	street and S19	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/16 12:09
S21	846	(438/460).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/16 12:09
S22	308	laser and S21	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/16 12:09
S23	11	("2911773" | "3081586" | "3852876" | "3970819" | "3991296" | "4019248" | "4135291" | "4217689" | "4237601").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/16 12:31
S24	20	("4355457").URPN.	USPAT	OR	ON	2005/08/16 12:32
S25	36	("4610079").URPN.	USPAT	OR	ON	2005/08/16 12:34
S26	7	("5785796").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/16 14:39
S27	9	("20010040152" | "20020115235" | "4610079" | "5543365" | "6211488" | "6252197" | "6271102" | "6407360" | "6512196").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/02 08:11
S28	36	("4610079").URPN.	USPAT	OR	ON	2006/01/02 08:12
S29	47	("4814296").URPN.	USPAT	OR	ON	2006/01/02 08:14

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S30	44	("20020086459" | "20020089054" | "20020125557" | "3838501" | "4015175" | "4104697" | "4249299" | "4292576" | "4312115" | "4670770" | "4721977" | "4729971" | "4814296" | "4837184" | "4846032" | "4900283" | "4949148" | "4985982" | "4992847" | "4996587" | "5000811" | "5019943" | "5095360" | "5160403" | "5216278" | "5217907" | "5219796" | "5272114" | "5369060" | "5477065" | "5706176" | "5786266" | "5804004" | "5814885" | "5843831" | "5858808" | "5904548" | "5922224" | "5943591" | "5998238" | "6049124" | "6055976" | "6252302" | "6265119").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/02 08:27
S31	1383	(combined or combination) and saw and dicing and laser	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/02 09:25
S32	180	((melt or melted or melting) and (saw or sawing or cut or cutting) and (wafer or substrate) and semiconductor).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/02 09:24
S33	4	laser near4 dicing adj tape	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/02 09:26
S34	14145	seimitsu.as.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/02 09:28

EAST Search History

S35	78856	laser and cutting	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/02 09:28
S36	5307	dicing and tape	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/02 09:28
S37	1130	S35 and S36	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/02 09:28
S38	902	semiconductor and S37	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/02 09:28
S39	387	(melt or melting or melted) and S38	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/02 09:29
S40	2022	tape and dicing and laser	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/06 15:42
S41	1085905	melt or melting	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/06 15:43
S42	707	S40 and S41	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/06 15:44

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S43	836398	chip or chipping	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/06 15:49
S44	584	S42 and S43	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/06 15:44
S45	22088	(chip or chipping) same (melt or melting)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/06 15:50
S46	190	S40 and S45	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/06 16:18
S47	48	chipping near4 melting	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/06 16:19
S48	4	("6220139").URPN.	USPAT	OR	ON	2006/04/06 16:22
S49	13	("3367216" | "3576061" | "3651841" | "4236432" | "4802396" | "4827822" | "4958546" | "5062338" | "5351592" | "5410935" | "5603252" | "5606900").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/06 16:26
S50	7	(wafer and blade and laser and melting).clm.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/06 16:27